DATA SHEET

SUNGMUN CODE : NSI-10S

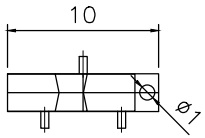
DESCRIPTION : SLIDE SWITCH

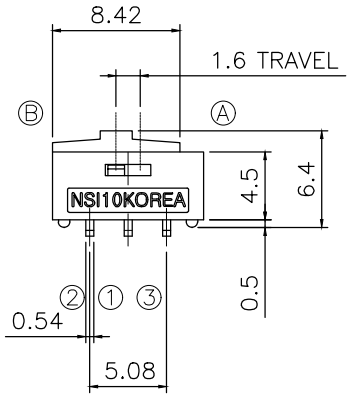
SUNGMUN ELECTRONICS CO., LTD.

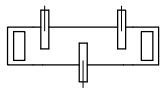
Address 301-302,Bucheon Technopark 345, Seokcheon-ro, Ojeong-gu
Bucheon-si, Gyeonggi-do, Korea
TEL. +82-32-328-1941~4
FAX +82-32-328-1945
E-mail sungmun@sungmun.co.kr
Website www.sungmun.com

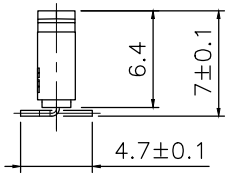
SUNGMUN ELECTRONICS

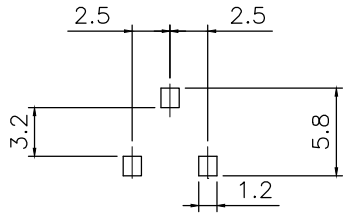
MRK.	DATE	REVISION	SIGN
△			



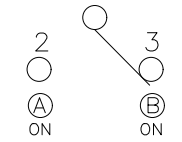








10--S P.C.B
DIMENSION



Circuit Diagram

SPECIFICATION

1. Rating : 0.5A, DC 12V~0.3A, DC24V
2. Contact Resistance : 30mΩ Max
3. Travel : 1.6mm
4. Operating Force : 800gf Max
5. Life cycle : 1,000 Cycle(with load)

DRAW/DESIGNED	CHECKED	APPROVED		G.TOL	TITLE	SLIDE SWITCH NSI-10	
			UNIT	SCALE	MODEL	NSI-10--S	SHEET
2016-01-22			mm	–			
SUNGMUN ELECTRONICS CO.,LTD				SIZE A4	DRAW NO.	NSI-10--S	1/1

SUNGMUN ELECTRONICS	NSI SERIES SLIDE SWITCH SPECIFICATION	Rev. 01 P : 1 / 2

1. Electrical Characteristics :
   - 1.1 Rating : AC, DC 12V 0.5A~24V 0.3A (Minimum current: 1mA)
   - 1.2 Contact Resistance : Max 30 mΩ
   - 1.3 Insulation Resistance : Min 10,000 MΩ at DC 500V
   - 1.4 Withstanding Voltage : 1min at AC 500V

2. Mechanical Characteristics :
   - 2.1 Operating Force : 250gf ± 150gf
   - 2.2 Travel : 1.6mm
   - 2.3 Insulator :
     - 2.3.1 Case : Glass Fiber resin
     - 2.3.2 Slide : Glass Fiber resin
   - 2.4 Terminal : Nickel, Gold Plate

3. Life Test :
   - 3.1 Test Condition : Operations at a rate of 15-20 cycles in 1 minute
     - 3.1.1 With load : 2,000 cycles
     - 3.1.2 Without load : 10,000 cycles
   - 3.2 Operating Force : With +40%, -40% of Initial Value
   - 3.3 Contact Resistance : Max 200mΩ

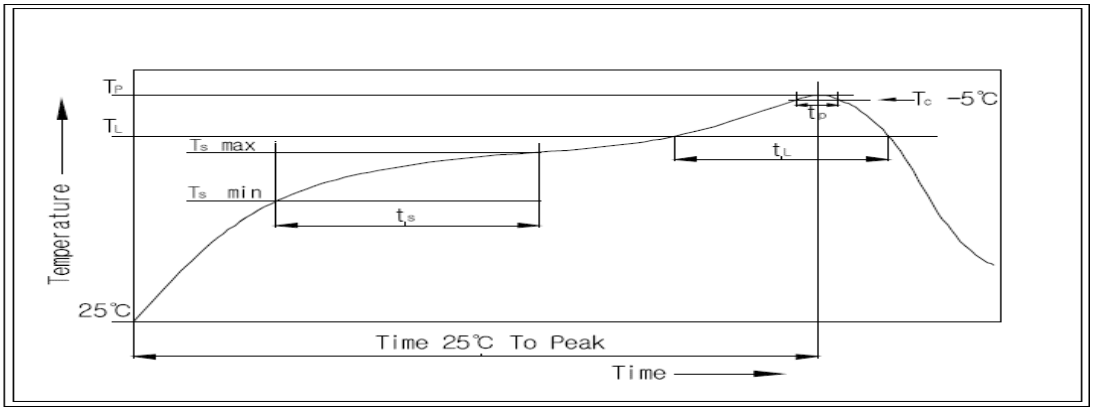
4. Environmental Characteristics :
   - 4.1 Operating Temperature : -40℃ to +85℃
   - 4.2 Storage Temperature : -40℃ to +85℃
   - 4.3 Humidity Test :
     - 4.3.1 Test Conditions : Measured 1hour after exposure to ambient
       After 96hours exposure at 40±2℃, 90-95% R.H
     - 4.3.2 Insulation Resistance : Min 100MΩ, at DC 500V
     - 4.3.3 Withstanding Voltage : 1min at AC 250V

5. Solder Conditions :

5.1 Hand Solder : 3~4 sec. at 350℃

5.2 Wave Solder : 5 sec. at 260℃

5.3 Reflow Solder



5.3.1 Condition for Soldering

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Ts max to TP)	3℃/second max
Preheat - Temperature Min(Ts min) - Temperature Max(Ts max) - Time (ts min to ts max)	 150℃ 200℃ 60-180seconds
Time maintained above: - Temperature (TL) - Time (tL)	 217℃ 60-150seconds
Peak/Classification Temperature(TP)	260℃ +0℃/ -5℃
Time within 5℃ of actual Peak Temperature(TP)	5~10 seconds
Ramp-Down Rate	6℃/sec max
Time 25℃ to Peak Temperature	8 minutes max